

SUBMINIATURE SOLID STATE LAMP

PRELIMINARY SPEC



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Part Number: AM27VGC/A03 Green

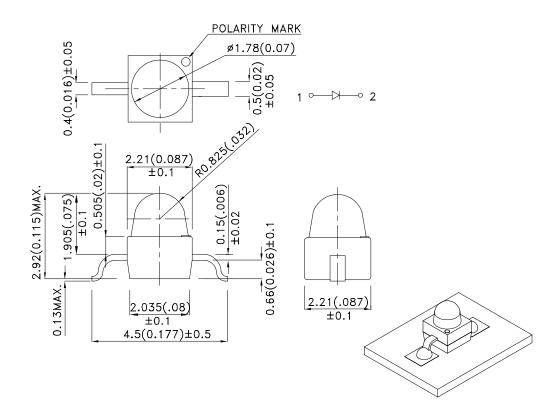
Features

- SUBMINIATURE PACKAGE.
- GULL WING.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE :1000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- RoHS COMPLIANT.

Description

The Green source color devices are made with InGaN on G-SiC Light Emitting Diode.
Static electricity and surge damage the LEDS.
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.





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 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Y.L.LI
 ERP: 1202001493

Selection Guide

Part No.	Dice	Lens Type		lv (mcd) [2] @ 20mA			Viewing Angle [1]
			Min.	Тур.	201/2		
AM27VGC/A03	Green (InGaN)	WATER CLEAR	380	800	20°		

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	520		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	525		nm	I=20mA
Δλ1/2	Spectral Line Half-width	Green	35		nm	IF=20mA
С	Capacitance	Green	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	3.2	4	V	I=20mA
lR	Reverse Current	Green		10	uA	V _R =5V

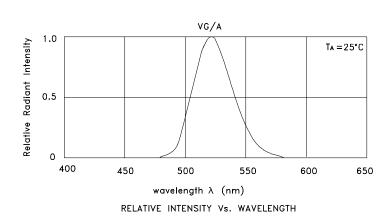
- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

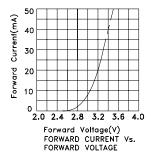
Parameter	Green	Units	
Power dissipation	120	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	100	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

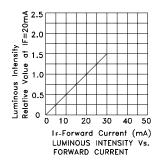
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

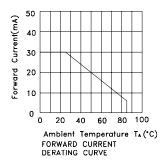
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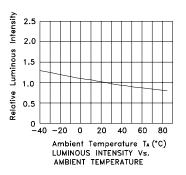


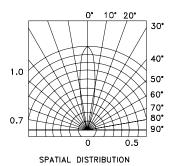
Green AM27VGC/A03











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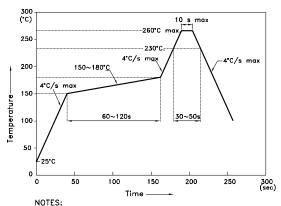
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AM27VGC/A03

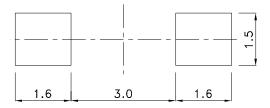
Reflow Soldering Profile For Lead-free SMT Process.



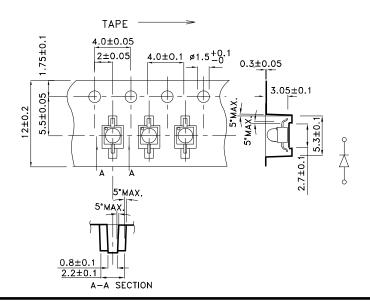
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



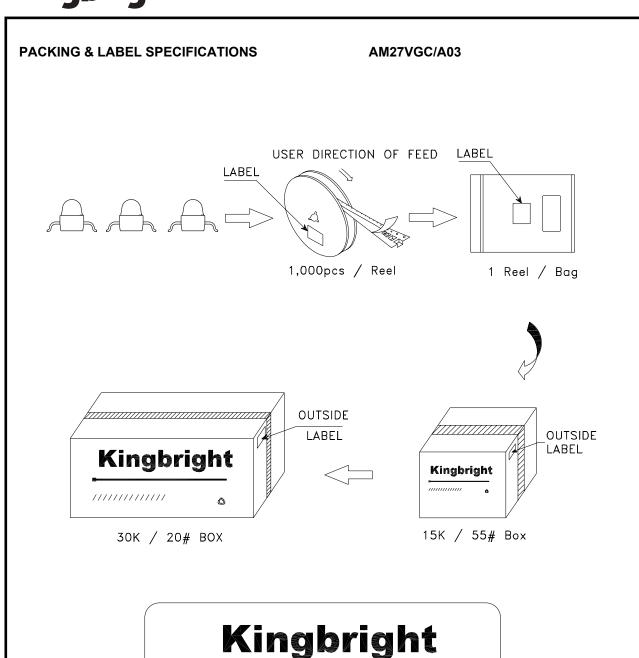
Tape Specifications (Units: mm)



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